



# SSC8K23GN2

## P-Channel Enhancement Mode MOSFET with Schottky Diode

### ➤ Features

#### P-Channel

VDS	VGS	RDSON Typ.	ID
-20V	±8V	135mR@-4V5	-2A
		180mR@-2V5	
		240mR@-1V8	

#### Schottky

VR	IR	VF Typ.	IO
20V	15uA	410mV @0.5A	1A

### ➤ Description

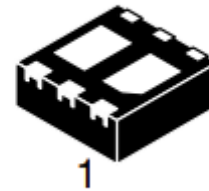
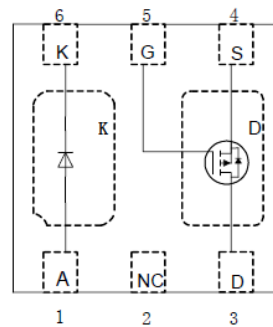
SSC8K23GN2 combines a P-Channel enhancement mode power MOSFET which is produced with high cell density and DMOS trench technology and a low forward voltage schottky diode. The tiny and thin outline saves PCB consumption.

### ➤ Applications

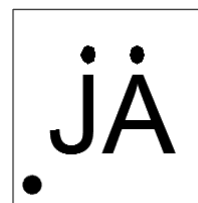
- Li-Battery Charging
- High Side DC/DC Converter
- High Side Driver for Brushless DC motor
- Power Management in Portable, Battery Powered Devices

### ➤ Pin configuration

Top view



Bottom View



Marking

### ➤ Ordering Information

Device	Package	Shipping
SSC8K23GN2	DFN2X2	3000/Reel



➤ **Absolute Maximum Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Ratings	Unit
P-MOS			
$V_{DSS}$	Drain-to-Source Voltage	-20	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 8$	V
$I_D$	Continuous Drain Current	-2	A
$I_{DM}$	Pulsed Drain Current	-8	A
Schottky Diode			
$V_R$	Schottky Reverse Voltage	20	V
$I_F$	Schottky Continuous Forward Current	1	A
Power Dissipation and Temperature			
$P_D$	Power Dissipation	1.1	W
$T_J$	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
$T_{STG}$	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance	115	$^{\circ}\text{C}/\text{W}$

➤ **Electronics Characteristics**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

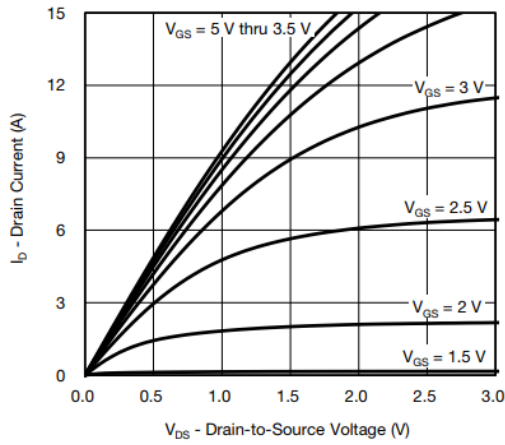
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
Schottky						
BV	Reverse Breakdown Voltage	$I_R=100\mu\text{A}$	20			V
$V_F$	Forward Voltage Drop	$I_F=0.5\text{A}$		0.41	0.45	V
$I_R$	Maximum reverse leakage current	$V_R=20\text{V}$		15	200	$\mu\text{A}$



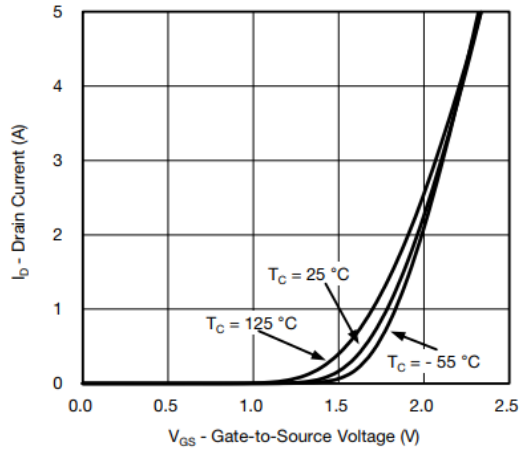
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
<b>P-Channel Enhancement Mode MOSFET</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.5	-0.7	-1.2	V
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=-4.5V, I_D=-1A$		135	190	mR
		$V_{GS}=-2.5V, I_D=-1A$		180	250	
		$V_{GS}=-1.8V, I_D=-1A$		240	500	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-20V, V_{GS}=0V$			-1	$\mu A$
$I_{GSS}$	Gate-Source leak current	$V_{GS}=\pm 8V, V_{DS}=0V$			$\pm 100$	nA
$G_{FS}$	Transconductance	$V_{DS}=-10V, I_D=-1.7A$		7.1		S
$V_{SD}$	Forward Voltage	$V_{GS}=0V, I_S=-1A$			1.3	V
$C_{iss}$	Input Capacitance	$V_{DS}=-10V, V_{GS}=0V, f=1MHz$		450		pF
$C_{oss}$	Output Capacitance			180		
$C_{rss}$	Reverse Transfer Capacitance			90		
$T_{D(ON)}$	Turn-on delay time			20		
$T_r$	Turn-on rise time	$V_{DS}=-6V, V_{GS}=-4.5V, R_L=6R, R_G=6R, I_D=-1A$		30		ns
$T_{D(OFF)}$	Turn-off delay time			180		
$T_f$	Turn-off fall time			120		



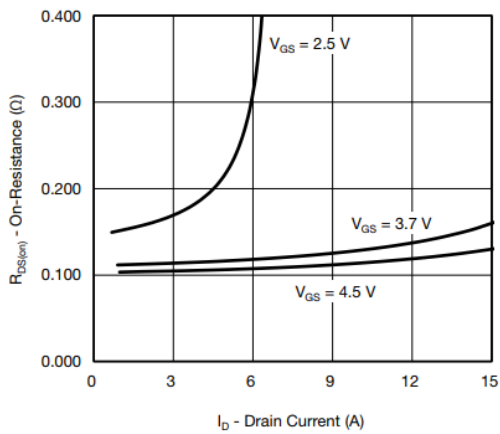
➤ **Typical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise noted)



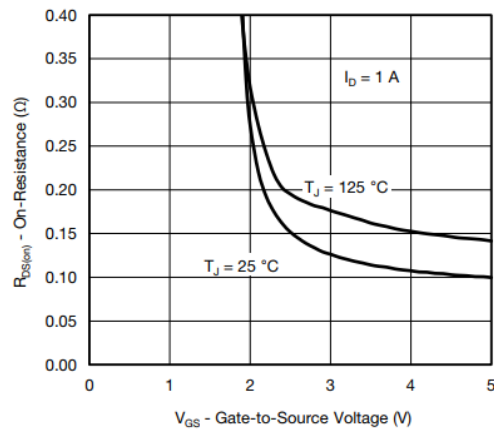
**Output Characteristics**



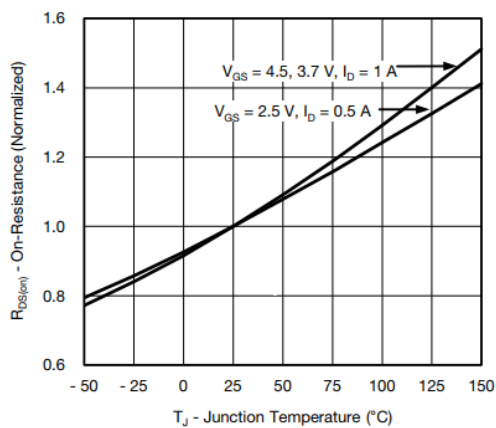
**Transfer Characteristics**



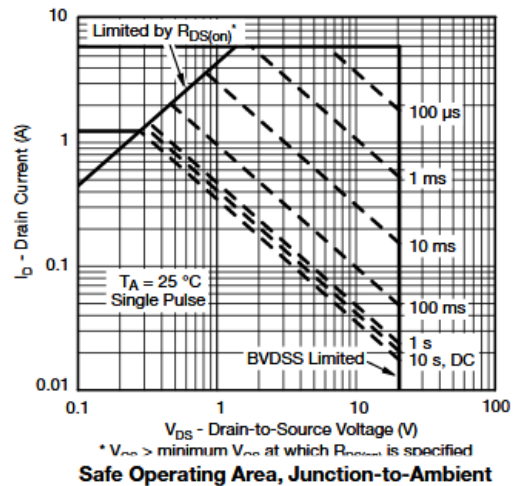
**On-Resistance vs. Drain Current and Gate Voltage**



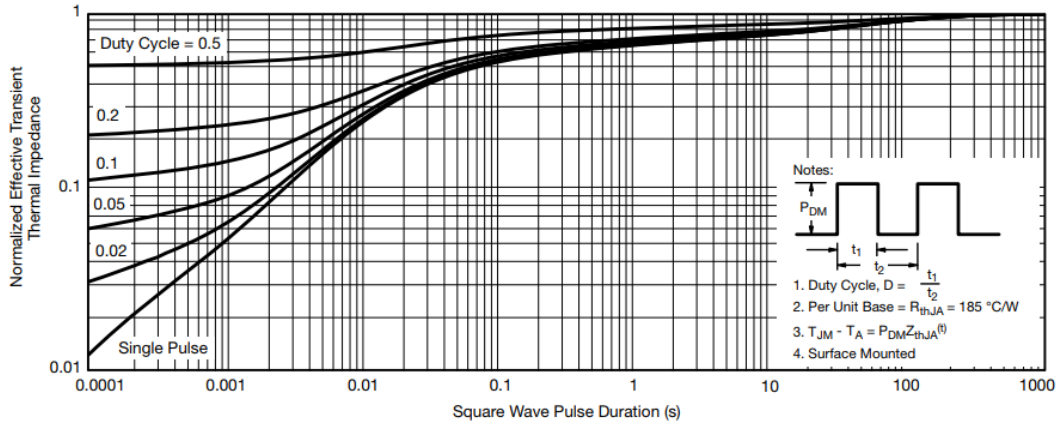
**On-Resistance vs. Gate-to-Source Voltage**



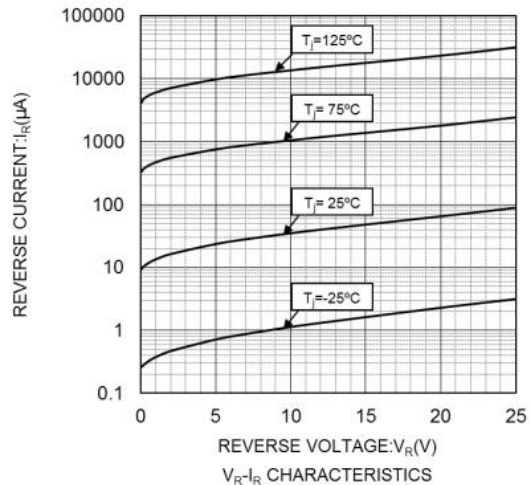
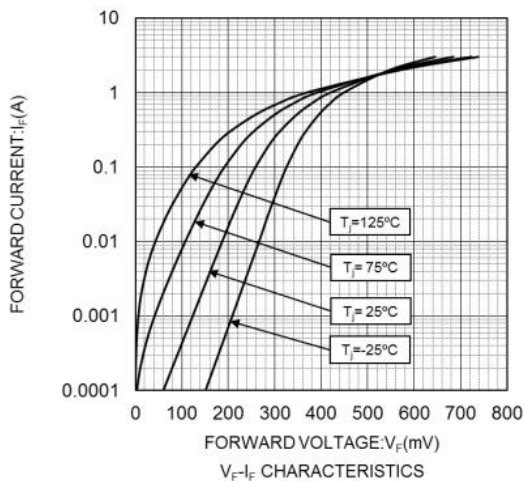
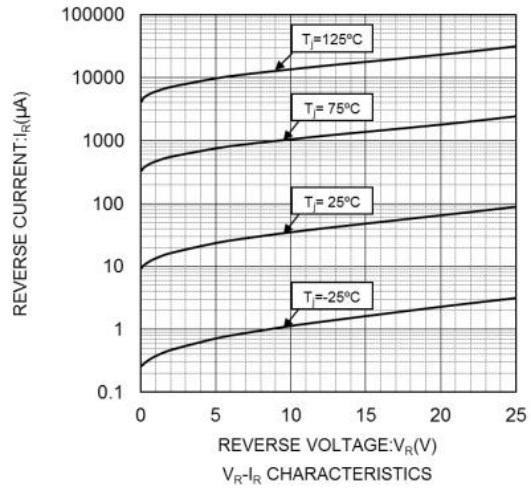
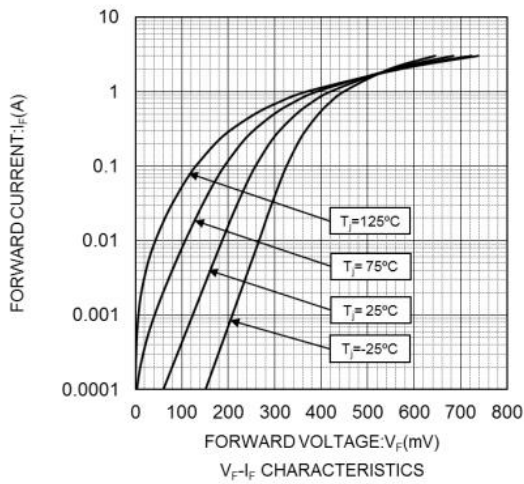
**On-Resistance vs. Junction Temperature**

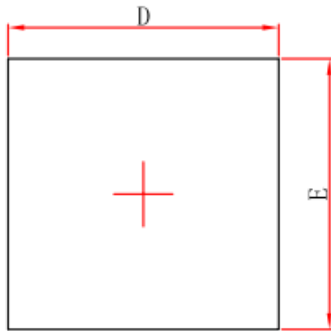
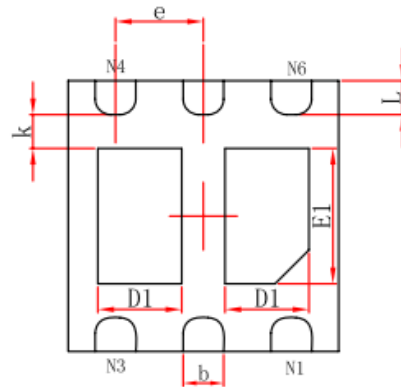
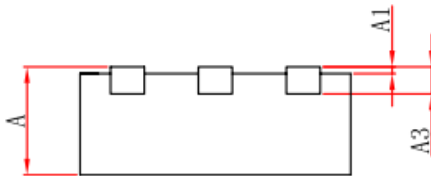


**Safe Operating Area, Junction-to-Ambient**



Normalized Thermal Transient Impedance, Junction-to-Ambient



**➤ Package Information**

**Top View**

**Bottom View**

**Side View**
**DFN2X2-6L**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.520	0.720	0.020	0.028
E1	0.900	1.100	0.035	0.043
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013



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